

EMLC - Online Event 2021

36th European Mask and Lithography Conference

Tuesday, June 22nd, 2021

Live PANEL SESSIONS with Live Q&A

Panel Session timing is chosen in order to allow live participation worldwide as much as possible.

After the event, Panel presentation slides will be uploaded to: www.emlc-conference.com

Video movies of the Panel Sessions will be uploaded to: www.vistec-semi.com

Panel Session times are indicated in the Central European Summer Time (CEST) zone.

08:00 – 11:15 PART 1

Pacific Time	Eastern Time	Ireland UK	CEST Israel	Russia Turkey	China Taiwan	Korea Japan
start: June 21 st 11:00 PM	start: June 22 nd 02:00 AM	start: June 22 nd 07:00 AM	start: June 22 nd 08:00 AM	start: June 22 nd 09:00 AM	start: June 22 nd 02:00 PM	start: June 22 nd 03:00 PM

08:00 CEST

 [hopin](https://hopin.com) meeting is opened by VDE-GMM meeting host Ms Hatice Altintas.

In case of questions, contact Ms Claudia Braeuer: claudia.braeuer@vde.com

08:05 – 08:15



Welcome by Uwe Behringer / UBC, EMLC 2021 Chair

08:15 – 09:30 1st EMLC 2021 PANEL on EUV LITHOGRAPHY



Panel Chair: Jo Finders / ASML (The Netherlands)



Panel Co-Chair: Albrecht Ehrmann / Carl Zeiss SMT (Germany)

PANEL TOPIC: EUV Lithography towards 2030.



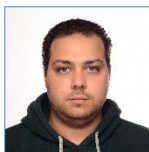
PANELIST: Gijbert Rispen / ASML (The Netherlands)
EUV system engineering imaging and resist



PANELIST: Ardavan Niroomand / IMEC (Belgium)
Program director for ASML/IMEC Advanced Patterning Center



PANELIST: Heiko Feldmann / Carl Zeiss SMT (Germany)
Head of Roadmap, initiating technology and product developments for semiconductor manufacturing equipment



PANELIST: Hazem Mesilhy / Fraunhofer IISB (Germany)
PhD student / researcher, computational lithography, High-NA EUV, mask 3D, optical simulations, multi-objective optimization



PANELIST: Renzo Capelli / Carl Zeiss SMS (Germany)
System Engineering, ZEISS Semiconductor Mask Solutions (SMS), EUV mask metrology



PANELIST: Jan van Schoot/ASML (The Netherlands)
Director EUV System Engineering

09:30 – 09:45 Break

09:45 – 11:15 2nd EMLC 2021 PANEL on EUV MASK TOPICS



Panel Chair: Jan Hendrik Peters / BMBG Consult (Germany)



Panel Co-Chair: Martin Tschinkl / TOPPAN Europe (Germany)

PANEL TOPIC: Readiness of the mask and lithography infrastructure for current and future EUV (phase shift masks and anamorphic) and suitable tools for mask making in EUV



PANELIST: Tilmann Heil / Carl Zeiss SMT (Germany)
Mask Repair; Mask Qualification; EUV: scaling for advanced nodes, High NA, phase shifting masks



PANELIST: Eelco van Setten / ASML (The Netherlands)
EUV imaging - specifically High-NA, mask contribution to imaging or EPE



PANELIST: Takahiro Onoue / HOYA (Japan)
EUV materials, especially PSM, transparent backside



PANELIST: Kei Hattori / SHIBAURA (Japan)
EUV clean and etch, material properties, layout requirements



PANELIST: Joost Bekaert / IMEC (Belgium)
Stitching and black borders, CNP pellicle, contour metrology, OPC



PANELIST: Dong Gun Lee / ESOL (South Korea)
EUV phase shift measurements

11:15 – 14:30 CASUAL MEETINGS during the BREAK

Between the morning and afternoon session you have the possibility to casually meet with your peers in the [meeting space](#) wonder.me provided by the conference committee.

Just join with audio and video connected, move around and join in small discussion circles. You will be automatically placed in a zoom like video chat with your colleagues within these circles.

14:30 – 17:45 PART 2

Pacific Time start: June 22 nd 05:30 AM	Eastern Time start: June 22 nd 08:30 AM	Ireland UK start: June 22 nd 01:30 PM	CEST Israel start: June 22 nd 02:30 PM	Russia Turkey start: June 22 nd 03:30 PM	China Taiwan start: June 22 nd 08:30 PM	Korea Japan start: June 22 nd 09:30 PM
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14:30 CEST [hopin](#) meeting is opened by VDE-GMM meeting host Ms Hatice Altintas.

In case of questions, contact Ms Claudia Braeuer: claudia.braeuer@vde.com

14:35 – 14:45



Welcome by Uwe Behringer / UBC, EMLC 2021 Chair

14:45 – 16:00 **3rd EMLC 2021 PANEL on MANUFACTURING DATA ANALYTICS**



Panel Chair: Bertrand Le Gratiot / ST Microelectronics (France)



Panel Co-Chair: Serap Savari / Texas A&M University (USA)

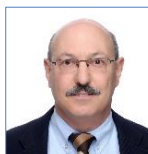
PANEL TOPIC: Turning Data into Silicon: The Digital Transformation of the Wafer Fabrication Processes



PANELIST: Philippe Leduc / STMicroelectronics (Singapore)
*Principal Engineer in Applied Mathematics & Scientific Computing,
Technical advisor for the Manufacturing Data Analytics program*



PANELIST: Benjamin Lenz / Infineon (Germany)
Infineon Technologies AG Head of Operations AI and Analytics



PANELIST: Harry J Levinson / HJL Lithography (USA)
*HJL lithography, LLC provides consulting and training services in
lithography and lithography process control*



PANELIST: Jelle Nije / ASML (The Netherlands)
*Sr product manager, Advanced Analytics portfolio enabling fast
time to insight and optimize decision making*



PANELIST: Clemens Utzny / KLA - QONIAN (Germany)
*Qoniac provides revolutionary lithography & patterning optimization
for the semiconductor industry*

16:00 – 16:15 **Break**

16:15 – 17:30 **4th EMLC 2021 PANEL on CAREER OPTIONS for YOUNG SCIENTISTS in the SEMICONDUCTOR LITHOGRAPHY INDUSTRY**



Panel Chair: Andreas Erdmann / Fraunhofer IISB (Germany)
Head of Fraunhofer IISB lithography and optics group



Panel Co-Chair: Ines Stolberg / Vistec Electron Beam (Germany)
Manager Sales & Marketing

PANEL TOPIC: Career opportunities for university young scientists and engineers in semiconductor lithography and mask industry



PANELIST: Rene Carpaij / ASML (The Netherlands)
Group Lead EUV Imaging



PANELIST: Jan Hoentschel / GLOBALFOUNDRIES (Germany)
Director Integration & Technology



PANELIST: Bertrand Le Gratiet / STMicroelectronics (France)
Fellow Lithography / Metrology



PANELIST: Hans-Jürgen Stock / Synopsys Munich (Germany)
Manager Research and Prototyping



PANELIST: Michael Woittennek / X-Fab (Germany)
Manager Operations



PANELIST: Holger Jennewein / Carl Zeiss SMT (Germany)
Director Optics Metrology

17:30 – 17:45 Final Remarks by Uwe Behringer / UBC, EMLC 2021 Chair



- Announcement of SPIE Photomask Technology ('BACUS') 2021
- Announcement of PMJ (PhotoMask Japan) 2022
- Announcement of EMLC 2022 conference at KU Leuven, Belgium, Monday, June 20th - Wednesday, June 22nd, 2022, and (optional) Visit at IMEC on Thursday, June 23rd, 2022

Co-operation Partners



Sponsors of the EMLC 2021

